

Residual Solvents Class 1

Rtx®-624 column.

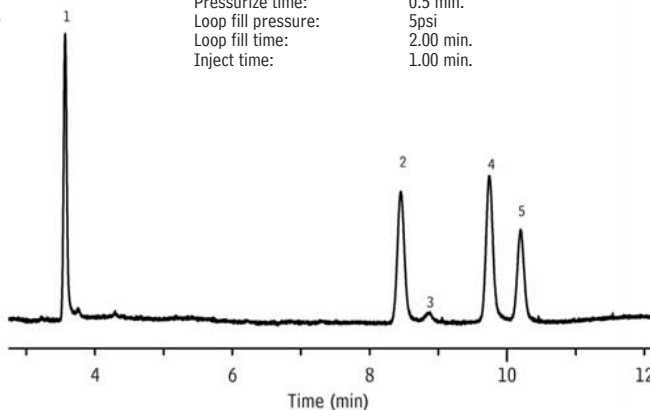
new!

Column: Rtx®-624, 30m, 0.32mm ID, 1.8 μ m (cat.# 10970)
 Sample: USP <467> Class 1 standard solution (cat.# 36279) in 20mL headspace vial headspace injection (split ratio 1:5), 1mm split liner, Siltek® deactivated (cat.# 20972-214.1)
 Inj.:
 Inj. temp.: 140°C
 Carrier gas: helium, constant flow
 Flow rate: 2.16mL/min., 35.3cm/sec.
 Oven temp.: 40°C for 20 min. to 240°C @ 10°C/min. (hold for 20 min.)
 Det.: FID @ 240°C

Headspace Conditions

Instrument: Tekmar HT3
 Transfer line temp.: 105°C
 Valve oven temp.: 105°C
 Sample temp.: 80°C
 Sample equil. time: 45 min.
 Vial pressure: 10psi
 Pressurize time: 0.5 min.
 Loop fill pressure: 5psi
 Loop fill time: 2.00 min.
 Inject time: 1.00 min.

1. 1,1-dichloroethene
2. 1,1,1-trichloroethane
3. carbon tetrachloride
4. benzene
5. 1,2-dichloroethane

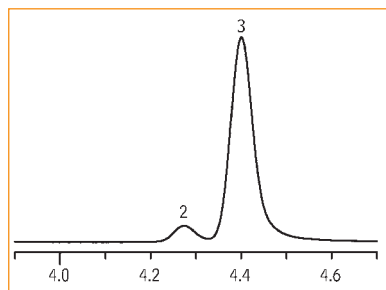


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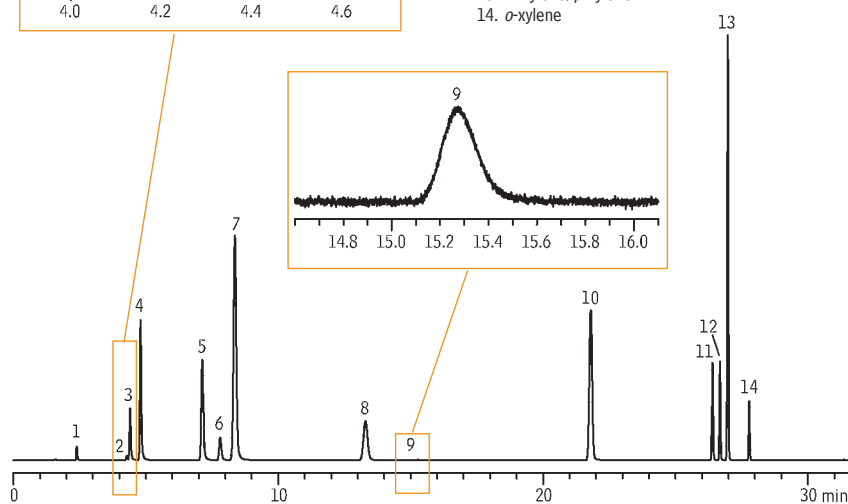
Residual Solvents Class 2 Mixture A

Rtx®-624

new!



1. methanol
2. acetonitrile (resolution=1.35)
3. dichloromethane
4. *trans*-1,2-dichloroethene
5. *cis*-1,2-dichloroethene
6. tetrahydrofuran
7. cyclohexane
8. methylcyclohexane
9. 1,4-dioxane
10. toluene
11. chlorobenzene
12. ethyl benzene
13. *m*-xylene/*p*-xylene
14. *o*-xylene



GC_PH00910

Column: Rtx®-624, 30m, 0.32 ID, 1.8 μ m (cat.# 10970)
 Sample: USP <467> Class 2 Mixture A standard solution (cat.# 36271) in 20mL headspace vial headspace injection (split ratio 1:5), 1mm split liner, Siltek® deactivated (cat.# 20972-214.1)
 Inj.:
 Inj. temp.: 140°C
 Carrier gas: helium, constant flow
 Flow rate: 2.16mL/min., 35.3cm/sec.
 Oven temp.: 40°C for 20 min. to 240°C @ 10°C/min. (hold for 20 min.)
 Det.: FID @ 240°C

Headspace Conditions

Instrument: Tekmar HT3
 Transfer line temp.: 105°C
 Valve oven temp.: 105°C
 Sample temp.: 80°C
 Sample equil. time: 45 min.
 Vial pressure: 10psi
 Pressurize time: 0.5 min.
 Loop fill pressure: 5psi
 Loop fill time: 2.00 min.
 Inject time: 1.00 min.